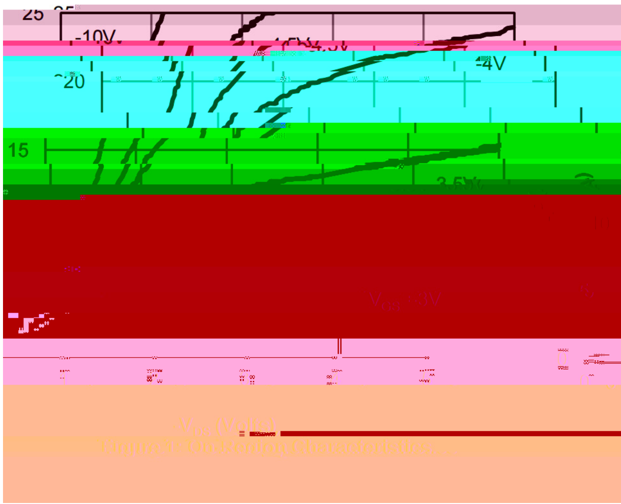
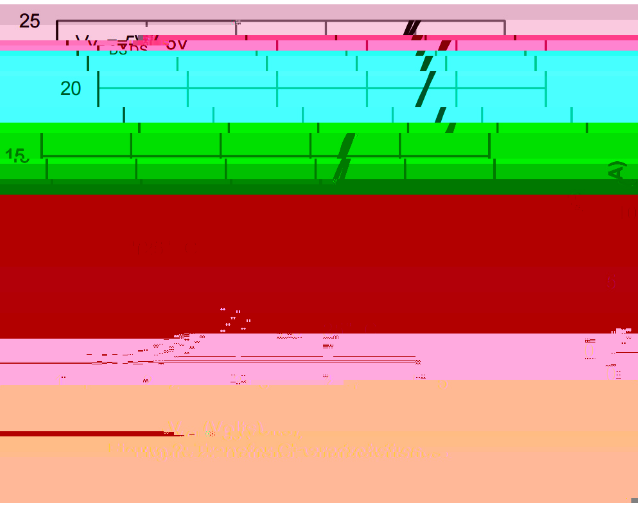
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	Q_g(10V)	V_{GS}=-10V, V_{DS}=-15V, I_D=-4.1A		8.5		nC
Total Gate Charge	Q_g(4.5V)			4.5		
Gate Source Charge	Q_{g}			1.5		
Gate Drain Charge	Q_{gd}			2.0		
Turn–On Delay Time	$t_{d(on)}$	V_{GS}				

/ Electrical Characteristic Curve





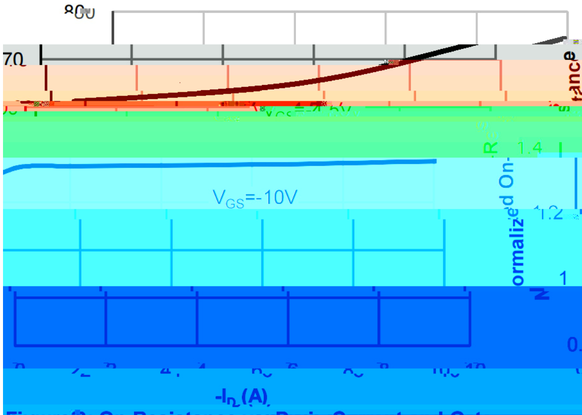


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

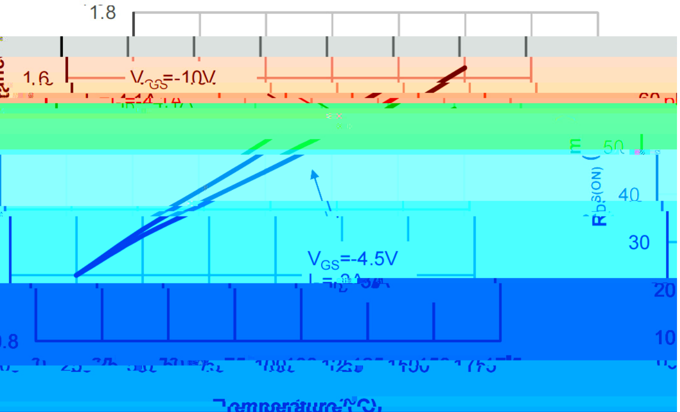
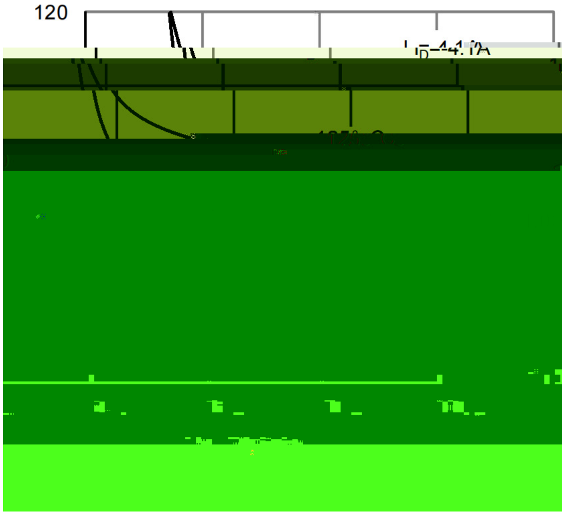
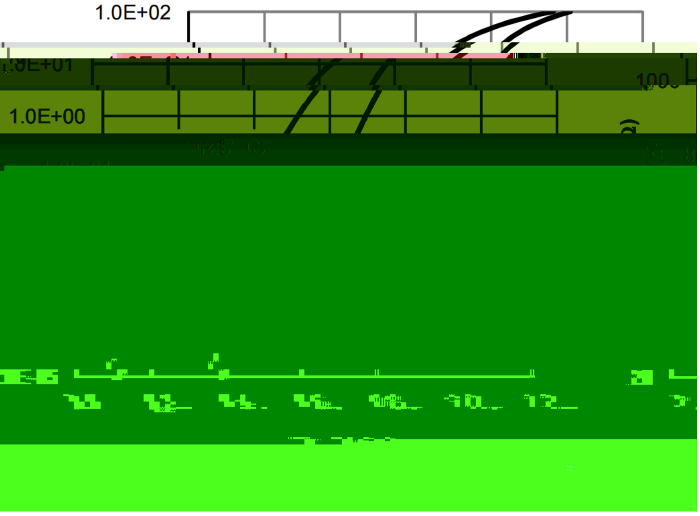
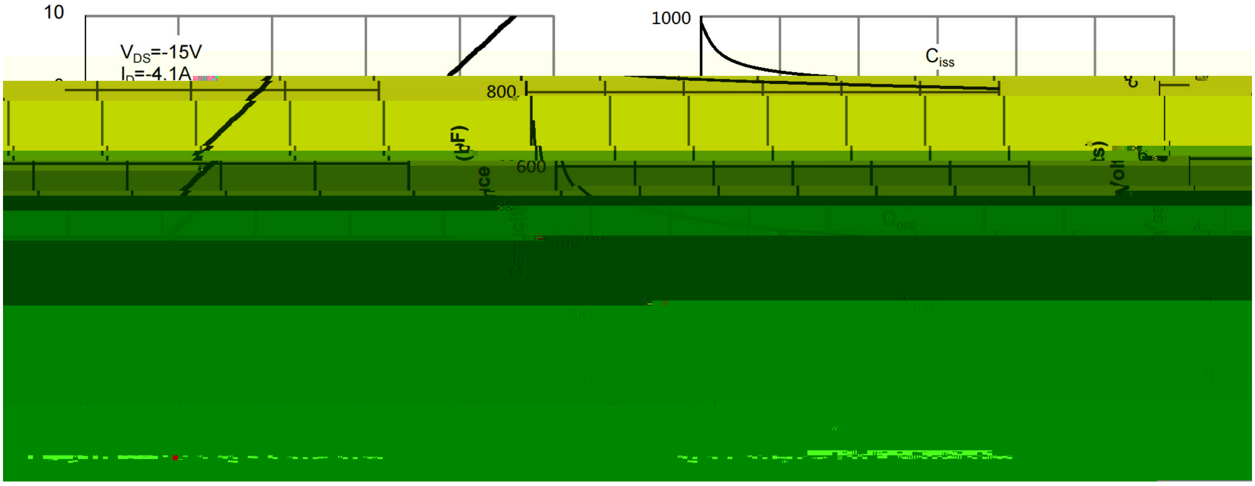


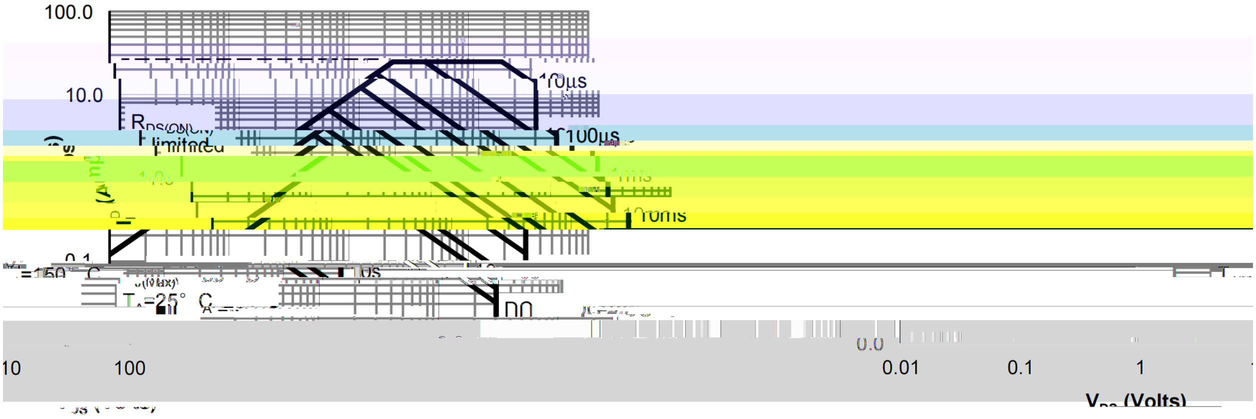
Figure 4: On-Resistance vs. Junction Temperature





/ Electrical Characteristic Curve

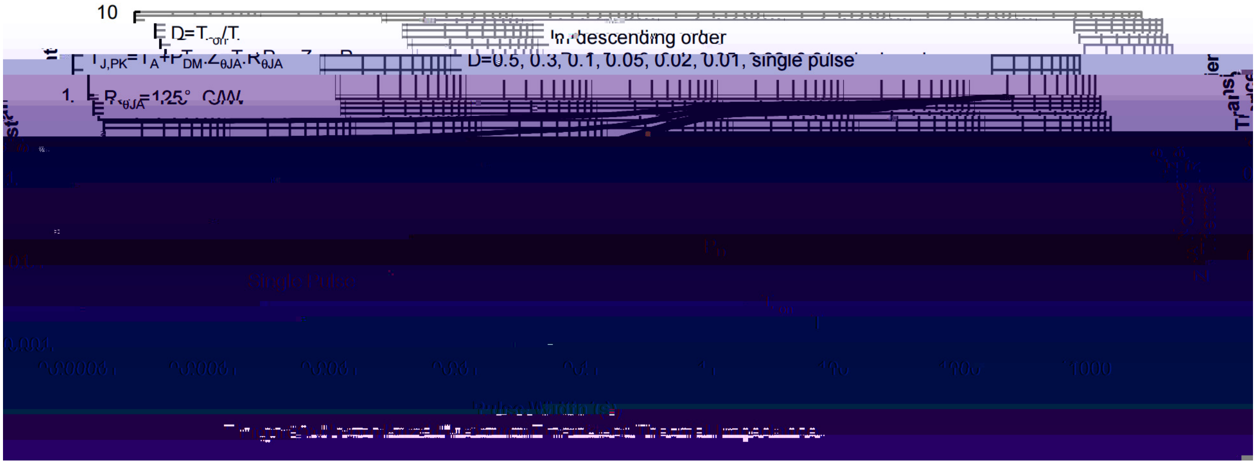




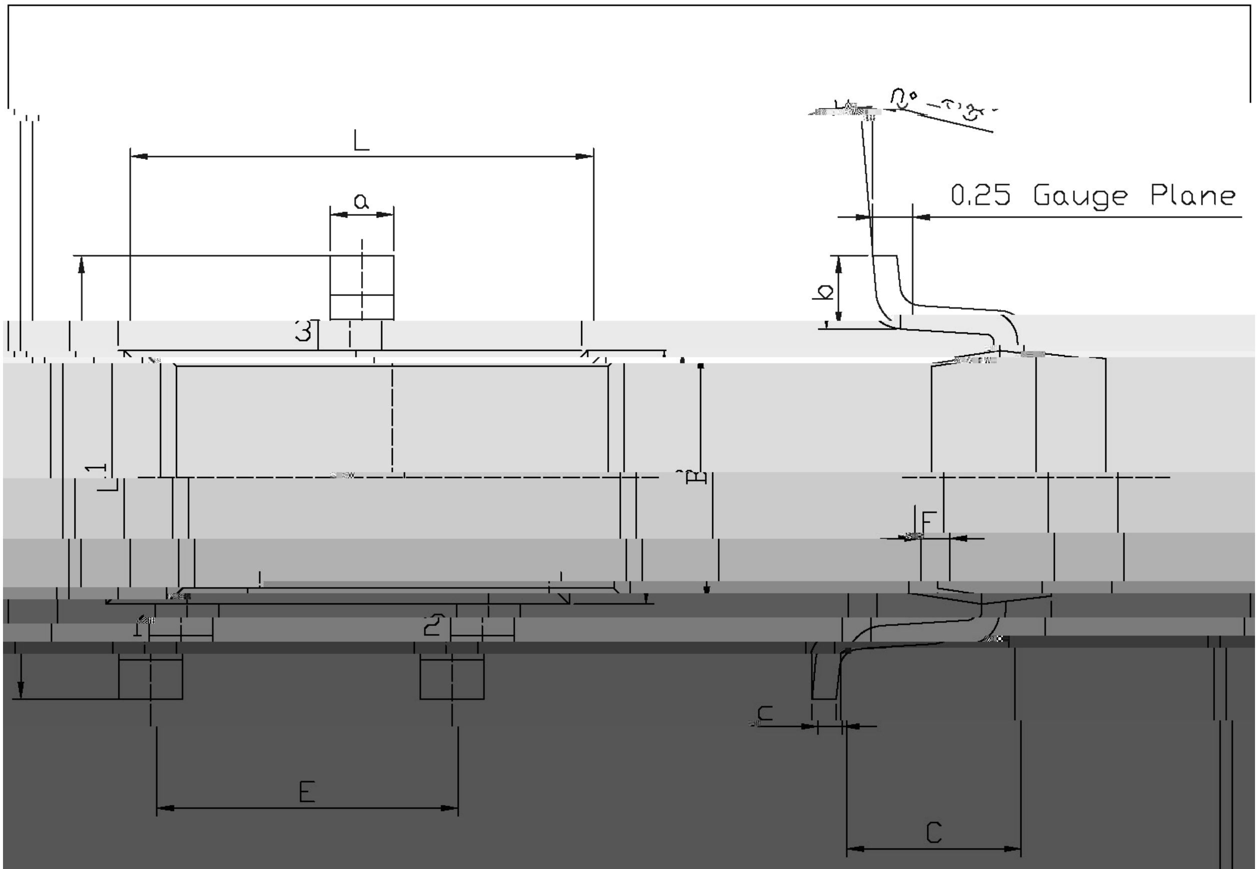
aximum Forward Biased Safe Operating Area

Figure 9: Ma

Operating Area



/ Package Dimensions



Unit: mm

[illegible]

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

	Note:
1 150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/q.`eREEL"†U #.À À)Ht2 SÆìQ5d… •AîPw›"Q 6

/c <0072004 Tc 0 Tj /TT2 1 Tf 2.0008 9ad041eTj /T3ceak